12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20250430002.1
Qualification of RFAB using qualified Process Technology, Die Revision, Datasheet and additional Assembly Site & BOM options for select devices
Change Notification / Sample Request

Date: May 01, 2025
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments (TI). The details of this change are on the following pages, and are in alignment with our standard product change notification (PCN) process.

TI requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification, given that samples are not built ahead of the change.

The Proposed First Ship date in this PCN letter is the earliest possible date that customers could receive the changed material. It is our commitment that the changed device will not ship before that date. If samples are requested within the 60 day sample request window, customers will still have 30-days to complete their evaluation regardless of the proposed 1st ship date.

Changes outlined in this notification underscore our commitment to product longevity and supply continuity, as well as our continued efforts to transition to newer, more efficient manufacturing processes and technologies. Specifically, this particular notification is related to TI's multiyear transition plan for our two remaining 150-millimeter production lines (DFAB in Dallas, Texas, and SFAB in Sherman, Texas). SFAB closure activities are expected to begin by the end of 2025. DFAB will remain open with a smaller set of 200mm technologies and GaN.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the Change Management team. For sample requests or sample related questions, contact your local Field Sales Representative. As always, we thank you for your continued business.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Change Management Team
SC Business Services

20250430002.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
UCC3803DTR	NULL
UCC2800DTR	UCC2800DTR
UCC3813DTR-2	NULL
UCC2801DTR	UCC2801DTR
UCC3813DTR-3	UCC3813DTR-3
UCC2813DTR-0	UCC2813DTR-0
UCC3813DTR-4	UCC3813DTR-4
UCC2813DTR-1	UCC2813DTR-1
UCC2813DTR-3	NULL
UCC2802DTR	UCC2802DTR
UCC3800DTR	UCC3800DTR
UCC2803DTR	UCC2803DTR
UCC2813DTR-2	UCC2813DTR-2
UCC3801DTR	UCC3801DTR
UCC2803PWTR	595-UCC2803PWTR
UCC2813DTR-4	NULL
UCC2804DTR	UCC2804DTR
UCC3802DTR	UCC3802DTR
UCC2813DTR-5	UCC2813DTR-5
UCC3813PWTR-0	UCC3813PWTR-0
UCC2805DTR	UCC2805DTR
UCC3813PWTR-0	595-UCC3813PWTR-0
UCC3804DTR	UCC3804DTR

Technical details of this Product Change follow on the next page(s).

PCN Number:	20250430002.1	PCN Date:	May 01, 2025
Title:	Qualification of RFAB using qualified Process Technology, Die Revision, Datasheet and additional Assembly Site & BOM options for select devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	July 30, 2025	Sample requests accepted until:	June 30, 2025*

***Sample requests received after June 30, 2025 will not be supported.**

Change Type:

☒	Assembly Site	☒	Design	☐	Wafer Bump Material
☒	Assembly Process	☒	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☒	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☒	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☒	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the addition of RFAB using the LBC9 qualified process technology and additional Assembly Site/BOM options for the devices listed below.

Current Fab Site			Additional Fab Site		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab Site**	**Process**	**Wafer Diameter**
SFAB	IMP-PWR1	150 mm	RFAB	LBC9	300 mm

The die was also changed as a result of the process change.

Construction differences are as follows:

Group 1 Device:

	Current	Additional
Wire diam/type	0.96mil Cu	0.80mil Cu
Pin 1 ID marking	Stripe	Dot
Top side marking		
Pin 1 ID marking	Stripe	Dimple

Group 2 Device:

	UTL2	MLA
Wire diam/type	1.0mil Au	0.80mil Cu
Mount compound	SID#PZ0013	4147858
Mold compound	SID#CZ0096	4211471
Pin 1 ID marking	Unitrode logo	TI letter

The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The links to the revised datasheets are available in the table below.

Changes from Revision G (May 2020) to Revision H (April 2025) **Page**

- Updated the numbering format for tables, figures, and cross-references throughout the document..... 1
- Added TSSOP package info to Device Information table in *Description* section..... 1
- Removed power dissipation info for L, N, and J packages in *Absolute Maximum Rating* section..... 6
- Updated T_A and removed T_J in *Recommended Operating Conditions* section..... 6
- Updated thermal resistance of D package in *Thermal Information* section..... 7
- Added "Vref vs Temperature" and "Error Amp. Input vs Temperature" figures in *Typical Characteristics* section 9

Changes from Revision F (May 2020) to Revision G (April 2025) **Page**

- Updated the numbering format for tables, figures, and cross-references throughout the document..... 1
- Added operating free-air temperature in *Recommended Operating Conditions* section..... 4
- Updated thermal resistance of D and PW packages in *Thermal Information* section..... 5
- Added "Vref vs Temperature" and "Error Amp. Input vs Temperature" figures in *Typical Characteristics* section 7

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
UCC280x	SLUS270G	**SLUS270H**	http://www.ti.com/product/UCC2801
UCCx813-x	SLUS161F	**SLUS161G**	http://www.ti.com/product/UCCx813-0

Qual details are provided in the Qual Data Section.

Reason for Change:

These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
SH-BIP-1	SHE	USA	Sherman
RFAB	**RFB**	**USA**	**Richardson**

Die Rev:

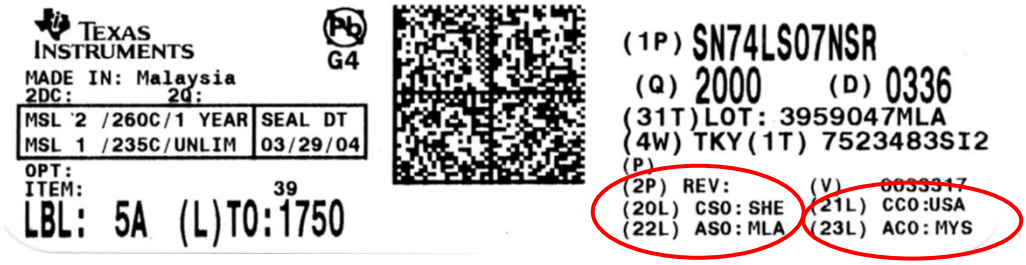
Current	New
Die Rev [2P]	**Die Rev [2P]**
-	**B**

Assembly Site Information:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
UTL2	NS2	THA	Bangpakong,

			Chachoengsao
TI Malaysia	**MLA**	**MYS**	**Kuala Lumpur**

Sample product shipping label (not actual product label):



Product Affected:

Group 1 Device:

UCC2800DTR	UCC2813DTR-0	UCC3800DTR	UCC3813DTR-0
UCC2801DTR	UCC2813DTR-1	UCC3801DTR	UCC3813DTR-1
UCC2802DTR	UCC2813DTR-2	UCC3802DTR	UCC3813DTR-2
UCC2803DTR	UCC2813DTR-3	UCC3803DTR	UCC3813DTR-3
UCC2804DTR	UCC2813DTR-4	UCC3804DTR	UCC3813DTR-4
UCC2805DTR	UCC2813DTR-5	UCC3805DTR	UCC3813DTR-5

Group 2 Device:

UCC2803PWTR	UCC2813PWTR-1	UCC3801PWTR	UCC3813PWTR-5
UCC2804PWTR	UCC2813PWTR-3	UCC3804PWTR	
UCC2805PWR	UCC2813PWTR-4	UCC3813PWTR-0	
UCC2813PWTR-0	UCC2813PWTR-5	UCC3813PWTR-3	

For alternate parts with similar or improved performance, please visit the product page on TI.com

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: UCC2802DTR	QBS Reference: PCM6260QRTVRQ1	QBS Reference: MC33063AQDRQ1	QBS Reference: UCC2802QDRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	1/77/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	1/77/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	3/231/0	3/231/0	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	3/135/0	1/77/0
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	3/231/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	3/2400/0	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	1/15/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	1/15/0	1/15/0

Type	#	Test Name	Condition	Duration	Qual Device: UCC2802DTR	QBS Reference: PCM6260QRTVRQ1	QBS Reference: MC33063AQDRQ1	QBS Reference: UCC2802QDRQ1
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	1/22/0	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	3/30/0	1/10/0
ESD	E2	ESD CDM	-	500 Volts	-	1/3/0	1/3/0	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	1/6/0	1/6/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	3/90/0	3/90/0	3/90/0

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device UCC2802DTR is qualified at MSL1 260C
- Qual Device UCC2803DTR is qualified at MSL1 260C
- Qual Device UCC2805DTR is qualified at MSL1 260C
- Qual Device UCC2803PWTR is qualified at MSL1 260C
- Qual Device UCC2805PWR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2310-030

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

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